

Guru Gobind Singh Indraprastha University

("A State University established by Govt. of NCT of Delhi") Sector 16-C, Dwarka, New Delhi-110 078



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Dated:23.01.2024

TENDER No.04 /PUR/GGSIPU/2023-24

E-TENDER (NIT)

Registrar, Guru Gobind Singh Indraprastha University invites e-tender from reputed and eligible contractors/firms in two bid systems (Technical & Financial) for the **Supply and Installation of Lab Equipments for Electronics Lab, USAR, East Delhi Campus** at Guru Gobind Singh Indraprastha University, Surajmal Vihar, Delhi-110092. Tender document can also be downloaded from Delhi Govt. e-procurement website i.e. www.govtprocurement.delhi.gov.in. The details of Tender document can also be viewed from University Website http://www.ipu.ac.in.

1.	Name of work	Supply and Installation of Lab Equipments for Electronics Lab at USAR, East Delhi Campus of Guru Gobind Singh Indraprastha University, Surajmal Vihar, Delhi -110092	
2.	The last date and time of uploading technical and financial bid on e-procurement website.	12.02.2024 upto 01.00 p.m.	
3.	Date and time for opening of Technical bid	12.02.2024 at 2.30 p.m	
4.	Estimated Cost of Material	Rs. 50,09,250/-	
5.	The bids shall be submitted in two stages viz.(i) Technical bid (ii) Financial bid. Detailed specification of the item(s) to be supplied is placed at Section-III Annexure-G. The Technical & Financial bid should be uploaded on e-procurement website i.e. www.govtprocurement.delhi.gov.in (No documents need to be submitted in hard copy).		
6.	Financial bid shall be opened after notified, thereafter on e-tender website	evaluation of technical bid and the date & time will be www.govtprocurement.delhi.gov.in	

(REGISTRAR)



TENDER DOCUMENT

FOR

Supply and Installation of Lab Equipments for Electronics Lab, USAR, East Delhi Campus

AT

USAR, East Delhi Campus Guru Gobind Singh Indraprastha University [A state University under Govt. of NCT of Delhi] Surajmal Vihar, Delhi -110092

> Dy. Registrar (Purchase) Room No. L 010, Ground Floor, Library Block, GGSIPU, Sector 16C, Dwarka, New Delhi 110078 Contact Nos.011 25302149-150 Email: purchasebranch@ipu.ac.in

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NOTICE INVITING TENDER

Registrar, Guru Gobind Singh Indraprastha University (GGSIPU) invites e-tender (in two bid system – Part I & II) from reputed and experienced bidders /suppliers for the following on Supply & installation basis:

- 1. Particulars of Items: Details of the items with specification is mentioned at Annexure-G
- **2.** Completion period: Supply and installation within 30 days from the date of issue of award of the tender/issue of Purchase Order, whichever is later.
- **3. Availability of Tender Document:** Tender Documents with detail terms & conditions can be downloaded from Delhi govt. e-procurement website.
- 4. **Qualification of the Tenderer:** The bidder must upload the documents on e-procurement website as per the **tender clause 13**.
- **5.** Validity Period of Offer: The rates offered in Part II (Financial bid) should be valid for one hundred and eighty (180) days from the date of opening of Part I (Technical bid) of the Tender.
- **6.** Receipt and opening of Tenders: The Technical Bid will be opened on the same day at 02.30 pm.
- 7. GGSIPU reserve the right to accept or reject any or all the tenders wholly or partially without assigning any reason thereof.

SECTION-I

INSTRUCTIONS TO BIDDERS

8.0 Scope & Work

The work consists of:

- 8.1 Supply and Installation of Supply and Installation of Lab Equipments for Electronics Lab, USAR, East Delhi Campus at Guru Gobind Singh Indraprastha University, Surajmal Vihar, Delhi110 092 as per specification in Section-III (Annexure-G).
- 8.2 Comprehensive on-site **warranty** for a period of **60 months from** the last date of completion/installation for all the items supplied as certified by the University.

9.0 Definitions:

- 9.1 **GGSIPU** means Guru Gobind Singh Indraprastha University, Delhi
- 9.2 University means Guru Gobind Singh Indraprastha University, Delhi
- 9.3 **Employer** means the Registrar, GGSIPU and his successor
- 9.4 **Bidder** means the Manufacturer/Vendor/Firm
- 9.5 "Year" means "Financial year" unless stated otherwise.

10.0 Who can apply:

- 10.1 <u>If the bidder is a proprietary firm</u>, the application shall be signed by the proprietor with his full typewritten name and the full name of his firm with its current address, Contact details etc.
- 10.2 <u>If the bidder is a firm in partnership</u>, the application shall be signed by all partners of the firm with their full typewritten names and current addresses, or alternatively, by a partner holding power of attorney for the firm. In the latter case a certified copy of the power of attorney should accompany the application. In both cases, a certified copy of partnership deed and current address of all the partners of the firm should accompany the application.
- 10.3 If the bidder is a limited company or a corporation, the application shall be signed by a duly authorized person holding power of attorney for signing the application accompanied by a certified copy of the power of attorney. The bidder should also furnish a certified copy of the Memorandum and Articles of Association duly attested by a Public Notary.
- 10.4 Joint Venture/ Consortiums are not accepted.

11.0 Sealing and Marking of Bids

11.1 Technical bid must be submitted on e-procurement website of each item and the respective Bid-Securing Declaration form for EMD as per **Annexure-I.**

12.0 Bid Submission:

- 12.1 The document comprise of the technical bids alongwith Bid-Securing Declaration Form should be uploaded on e-procurement website i.e. www.govtprocurement.delhi.gov.in only (Not to be submitted in hard copy)
- Technical bid must be uploaded on e-procurement website and EMD (with validity of 180 days i.e. bid validity period +45 days) in FDR/DD/online only should be submitted in the office.
- 12.3 (i) The bidder shall submit "Earnest Money Deposit" alongwith covering letter in original (No other documents need to be submit in hard copy) in an envelope addressed to Dy. Registrar (Purchase), Guru Gobind Singh Indraprastha University, Sector 16-C, Dwarka, New Delhi-110078 only in case of EMD is in shape of FDR/ DD.
 - (ii) EMD can also be deposited in online mode in University Bank Account as per details below:-

RTGS/ECS Details			
1.	Accounts Holder Name	Registrar, Guru Gobind Singh Indraprastha University	
2.	Account No.	927860555	
3.	IFSC Code	IDIB000G082	

4.	Bank Name	Indian Bank
5.	MICR Code	110019071
6.	Account type	SB (Saving)
7.	CBS Code/ Branch Code	02029
8.	Branch Name & Address	GGSIPU, Sector-16C, Dwarka, New Delhi -110078
9.	Banker's Phone No.	011-28035244

- (iii) EMD EXEMPTION: The bidder seeking EMD exemption, must submit the valid supporting document for the relevant category of equipments with the bid. Under MSE category, only manufacturers for goods and Service Providers for Services are eligible for exemption from EMD. Traders are excluded from the purview of this Policy.
- 12.4 The envelope containing EMD shall indicate the name and address of the bidder to enable the bid to be returned unopened in case it is declared late or is declared non-responsive.
- 12.5 In case of submission of EMD Online (RTGS/ NEFT), there is no requirement of physical submission. A Declaration should be submitted with details of RTGS/ NEFT.
- 12.6 A pre-bid meeting shall be held on **30.01.2024 at 11:00 AM** in the Purchase Branch, GGSIPU University with the interested and prospective bidders to resolve their queries and issues clarification (if any).
- 12.7 The "Financial Bid" shall comprise of the price bids uploaded on e-tender website i.e. www.govtprocurement.delhi.gov.in
- 12.8 Each page of the Technical Bid, Tender Document must be signed by the authorized signatory of the bidder.
- 12.9 Conditions other than those laid down in the Tender document will not be entertained.

13.0 Eligibility Criteria for Technical Bid

The formats/Annexure for the documents to be submitted, with Technical bids are placed at (Annexure-A, A1, A2 to Annexure J):

13.1	Letter of Transmittal	Annexure – A
	Declaration by Bidder	Annexure - A1
	Compliance to Bid Requirement	Annexure - A2
	A declaration by the manufacturer/firm/vendor as to the probable date of manufacture of	Annexure – A 3
	the item for which financial bid has been made.	Annexure – A 3
	Organizational Structure: - Legal status of the company/ organization with legal proof along with certified copies.	Annexure - B
13.2	Income Tax Registration (PAN No.),	Attach certified
	GST Registration Number	copies
13.3	Average financial turnover of Rs. 68,00,000/- for the equipment during the immediate last three consecutive financial years, duly audited, signed & stamped by a Chartered Accountant. The bidder should not have incurred losses in more than two years in the last 3 consecutive financial years along with copies of audited profit and loss account of last three years.	Annexure C
13.4	Firm should have executed at least one of the following in the last three years: One single order of similar work having value of Rs.40,07,400/- OR Two similar work having value of Rs. 30,05,550/- OR Three similar work having value of Rs.20,03,700/- each Explanation: Same and Similar nature of equipment means the work of supply and installation of similar or equivalent equipments mentioned at Annexure-G in public sector undertaking, Govt. department, Educational Institutions, Research Institutional or in reputed private sector. This should be certified by an authorized officer of the client organization on its letter-head.	Annexure D
13.5	That the bidder/ organization has not been debarred or blacklisted by any of the Central/State Government/Departments /Organizations/Central or State PSU in last 3 years. In case the debarrement or blacklisted has been revoked by the department or court then it shall not be considered as blacklisting or debarrement. A declaration of fair business practice by the Bidder.	Annexure – E

13.6	An Undertaking (duly filled/ tick mark wherever applicable) is required to be submitted by the prospective bidders in the prescribed format as per Rule 144 (xi) of GFR 2017 regarding Restrictions on procurement from a bidder of a country which shares a land border with India, any bidder from a country which shares a land border with India will be eligible to bid in this tender only if the bidder is registered with the Competent Authority. While participating in bid, Bidder has to undertake compliance of this and any false declaration and non-compliance of this would be a ground for immediate termination of the contract and further legal action in accordance with the laws.	Annexure – J
13.7	The intending bidder must submit compliance report of each item of the bid.	Attach compliance report
13.8	The Manufacturer/firm/vendor should have a authorized service centre in India only	Attach copy of proof
13.9	Printed and proper circulated catalog for the quoted similar items be submitted along with the tender document	Attach copy of proof
13.10	Authorization letter of the OEM Upload Manufacturer authorization: Wherever Authorised Distributors are submitting the bid, Manufacturers Authorisation Form (MAF)/Certificate with OEM details such as name, designation, address, e-mail Id and Phone No. required to be furnished along with the bid.	Attach copy of proof
13.11	Comprehensive on-site warranty for a period of 60 months from the last date of completion/installation for all the items supplied as certified by the University.	Certificate to be given
13.12	The proprietor/partners of the agency do not have any relative employee in the University.	Certificate to be given
13.13	The intending bidder must attach Income Tax return for the last three years with the bid document or Gross Annual Income Certificate for the last three years duly certified by the Charted Accountant	Attach copy of proof
13.14	Supplier needs to demonstrate the quoted instrument at the University and show each point mentioned in the technical specification. The quality of the equipments will be evaluated by the Technical Committee based on the physical demonstration by the bidder during the technical bid evaluation.	Attach copy of Acceptance
13.15	The bidder shall upload the printed brochure / catalogue of the offered equipment on official website.	Certificate to be given
13.16	The official link of website of OEM/ manufacturer is also required to be mentioned on the letter head of the bidder for the equipments quoted by the bidder.	Certificate to be given
13.17	MII Purchase Preference	No

All the documents should by self attested by the bidder. University reserves the right to independently verify the documents submitted by the bidder form issuing authority.

14.0 Opening of Technical Bids & Evaluation:-

- 14.1 The details submitted by the bidders will be evaluated in the following manner:
- 14.2 The "initial eligibility criteria" prescribed in para 13.1 to 13.17 above in respect of experience in similar class of works completed, financial turnover, profitability and valid registrations will first be scrutinized.
- 14.3 Examination of the specification of all the items will be done by specialized specification evaluation committee.
- 14.4 Even though any bidder may satisfy the above requirements, he/she would be liable to disqualification if he/she has:-
- 14.5 Made misleading or false representation or deliberately suppressed the information in the forms, statements and enclosures required in the eligibility criteria document.
- 14.6 Record of poor performance such as abandoning work, not properly completing the contract, or financial failures/weaknesses etc.

15.0 Opening of Financial bid and evaluation:

After the Technical evaluation of the bids, the University will open the 'Financial Bids' of all the bidders who have qualified in the Technical Eligibility Criteria as per Clause 13, at notified time, date and place, if any. The lowest financial bidder item-wise shall only be considered for award of work.

16.0 Earnest Money Deposit:

- 16.1 The Earnest Money Deposit (EMD) along with covering letter must be submitted in hard copy as per date and time mentioned above at **point No.12.3 to 12.5 and as per annexure-G.**
- 16.2 Tenders with no earnest money deposit will summarily be rejected. In case of successful bidder of the financial bids, the earnest money will be returned after obtaining the required 5% Performance Security in the form of FDR/BG (FDR/BG should be valid for a period of 62 months) from the date of installation.
- 16.3 In the case of unsuccessful bidders, the Earnest Money Deposit will be refunded without any interest.
- Those firms/ suppliers which are registered with MSME /MSE for the items mentioned in the tender document, are exempted for submission of EMD only and are required to submit a copy of valid registration certificate in place of EMD as per GFR 170(i) and clause 12 (iii) of the tender document.

17.0 Financial Bid:

The bidder shall quote unit item rates in INR only. No alterations in the form of tender, in the schedule of quantities or additions (Financial Bid) etc. shall be permitted. In case of difference between the rates of items written in figures and in words, the rates of items written in words shall be taken as correct. The rates quoted in schedule of quantity (Financial Bid) are for finished and completed items and no extra amount for cartage or transporting material, labour etc. shall be paid. The rates should be inclusive of all loads and lifts for all materials for the completed items and also include all taxes, insurance, royalties etc. as applicable. Indian Supplier has to quote the all inclusive of rate product i.e. freight, insurance, packing, handling, assembling, installation, commissioning upto the University or as given in the work order.

18.0 General:

- All information called for in the enclosed forms should be furnished against the relevant places in the forms. If for any reason, information is furnished on a separate sheet, this fact should be mentioned against at the relevant place. Even if no information is to be provided in a column, a "Nil" or "No Such Case" entry should be made in that column. If any particular/query is not applicable in case of the bidder, it should be stated as "not applicable". The bidders are cautioned that incomplete information called for in the tender document or deliberate suppression of any information may result in the bid being summarily disqualified. Bids received after the expiry of the stipulated date and time mentioned in the tender document will not be entertained.
- Overwriting should be avoided. Correction, if any, should be made by neatly crossing out, initialing with date and rewriting. Pages of the eligibility criteria document are to be numbered. Additional sheets, if any added by the bidder, should also be numbered. Bid should be submitted as a package with signed letter of transmittal.
- 18.3 References, information and certificates from the respective clients certifying suitability, technical knowledge or capability of the bidder should be signed by officer of the client organization with name & designation.
- 18.4 The bidder may furnish any additional information which he thinks is necessary to establish his capabilities to successfully complete the envisaged work. He is, however, advised not to furnish superfluous information. No information shall be entertained after submission of tender document unless it is called for by the University.
- Any information furnished by the bidder found to be incorrect either immediately or at a later date, would render him liable to be debarred from tendering/taking up of any work in GGSIPU which may also result in forfeiture of performance security.
- 18.6 The successful bidder shall have to work in co-ordination and co-operation with any other agencies appointed by the University to work simultaneously in the same or adjoining area. The decision of the University in case of any dispute between the different agencies appointed by the University shall be final and binding.
- 18.7 Income tax, Works Contract Tax and any other tax at the rates in force during the progress of contract / award of work that will be in force from time to time shall be recovered / deducted from the released payment amount.
- 18.8 GST or any other tax on material applicable on the date of submission of bid in respect of this contract shall be payable by the bidder and University will not entertain any claim whatsoever in respect of the same.

- 18.9 The bidder shall have to make his own arrangement at no extra cost to the University for water Supply & Installation, sanitation and electric Supply & Installation etc. at the site of work.
- 18.10 On acceptance of the tender, the name of the accredited representative(s) of the bidder who would be responsible for taking instructions from the University shall be communicated in writing to the Registrar.
- 18.11 If the bidder shall obtain a contract with GGSIPU as a result of wrong tendering or other non-bonafide methods of competitive tendering, the University reserves the right to terminate the contract without any liability to the bidder, which may also result to forfeiture of performance security.
- 18.12 Without prejudice to any of the rights or remedies under this contract if the bidder dies, the University shall have the option of terminating the contract without compensation to the legal heir of the bidder.
- 18.13 Escalation: Increase in rates of material / Labour shall not be payable on any account. Price quoted shall be firm and no escalation will be allowed on any account.
- 18.14 A bidder's bid security will be forfeited if the bidder: i) withdraws or amends its/ his tender; ii) impairs or derogates from the tender in any respect within the period of validity of the tender; iii) If the bidder does not accept the correction of his bid price during evaluation; and iv) If the successful bidder fails to sign the contract or furnish the required performance security within the specified period.

20.0 Scope of Works

The Scope of work shall consist, Supply & Installation, erection and placing in position at site, complete in all respects, and its maintenance during warranty period for items mentioned as per specification given under **Section III** and demonstration & training to the concerned staff/faculty.

20.1 Specification for Work and Quality

The procurement of various materials shall be either from the manufacturers or their main authorized dealers to ensure that no duplicate/spurious makes are used in the works. The entire work shall be warranted for a period of **60 months** against defective material with liability of replacement or to the satisfaction of the University.

20.2 Safety and Security

Safety and Security of workers/staff, material, equipments, etc. will be the responsibility of the bidder. The university will not be held responsible on this account

- 20.3 The University reserves the right, without being liable for any damages or obligation to inform the bidder, to:
 - (a) Amend the scope and value of contract to the bidder.
 - (b) Reject any or all the applications without assigning any reason.
- 20.4 Any effort on the part of the bidder or his agent to exercise influence or to pressurize the University would result in rejection of his bid. Canvassing to any kind is prohibited.
- 20.5 The necessary demonstration & training to the concerned staff/faculty and technical support will be provided for the period of maximum 1 week by the company.
- 20.6 All the necessary manuals, documentations (2 Sets) will be provided in hard and soft form by the supplier only.
- 20.7 The commissioning and complete installation of all the equipment/machinery, including civil work, electrical work, pneumatic power supply etc. as per the setup finalized by the committee will be done by the supplier only.
- 20.8 **Default in After Sales Services:** In the event of any default and/or unsatisfactory after sales service by the supplier/tenderer/vendor/firm, the competent authority of the institute will be at liberty to repair during warranty/get the item repaired/serviced from other source/party at the cost of vendor. All the cost has to be paid by the vendor / supplier of instrument.
- 20.9 In case of software items, the suppliers should ensure that:
 - a) Legal software is supplied in original sealed pouches/pkt.
 - b) A license agreement is enclosed with it
 - c) A registration card is available in software.

20.10 The bidder who will qualify the technical evaluation shall give demonstration of the equipments to the technical members of the committee. Price bids of only those bidders will be considered whose demonstration will be found satisfactory by the technical members of the committee.

21.0 Final decision making authority

The University reserves the right to accept or reject any bid and to annul the process and reject all bids at any time, without assigning any reason or incurring any liability to the bidders. No claim whatsoever will be entertained / paid by the university to the bidder (s).

22.0 Summary Rejection of tender:

22.1 The tenders not submitted the form for Bid-Securing Declaration for EMD (Annexure-I) shall be summarily rejected. Similarly, if the bidder proposes any alternation in or additions to the prescribed form of tender or decline to carry out any work of the tender document; or any conditions mentioned, etc., his tender is liable to be rejected.

23.0 Particular provisions

- 23.1 The University reserves the right to execute the work or reject the tender without assigning any reason or incurring any liability to the bidder.
- The University has the power to make alteration in, omission from, addition of or substitution for the original specifications, drawings, designs.

24.0 Amendment of tender document:

- 24.1 Before the deadline for submission of tender, the University may modify the tender document by issuing addenda.
- 24.2 Any addendum thus issued shall be a part of the tender document and shall be uploaded on the eprocurement website (www.govtprocurement.delhi.gov.in). Prospective bidders must visit the website before filling and submission of Tender Document for such information.

25.0 Validity of Tender:

One Eighty days from the date of opening of Technical Bid of the tender. During this period no bidder shall be allowed to modify/ withdraw his tender.

26.0 Performance Guarantee:

- 26.1 The successful bidder shall be required to furnish a Performance Guarantee of 5% after successfully installation of the product at site. The Performance Guarantee should be valid up to **60 days beyond warranty period i.e. 60 months**. The Performance Guarantee shall be accepted in the following form and shall be in favour of "Registrar, GGSIPU", payable at Delhi with a validity of months as under:
 - i. Fixed deposit receipt (FDR) of a nationalized bank
 - ii. Bank Guarantee (As per Annexure-H)
- 26.2 Performance Guarantee will be refunded after completion of the warranty period as per clause 27.
- 26.3 In case of non submission of Performance Guarantee within specified time the University may consider to black list/de-bar the bidder.
- 26.4 In case a fixed deposit receipt/ Bank Guarantee of any bank is furnished by the bidder to the University as part of the Performance Guarantee and the Bank is unable to make payment against the said instrument. The loss caused thereby shall fall on the supplier and the supplier shall forthwith on demand furnish additional security to the University to make good the deficit.

27.0 Warranty

The bidder shall provide comprehensive on-site **warranty** for a period of **60 months** for all items from the last date of completion/ installation as certificate issued by the University and shall be responsible for any defects that develop in the item. They shall also replace any defective part of the product supplied and other accessories, without any exception and recourse, free of cost.

The bidder is responsible for all packing, unpacking, assembly, installation of units. The bidder will test the products and accomplish the adjustments necessary for successful and continuous operation of the products supplied at all installation sites and shall ensure maintenance of the supplied products during the warranty period. All the repairing / replacing of defects shall be done by the bidder totally free of cost.

28.0 Option Clause

The University reserves the right to increase or decrease the quantity to be ordered up to 25 percent of bid quantity at the time of placement of contract. The purchaser also reserves the right to increase the ordered quantity by up to 25% of the contracted quantity during the currency of the contract at the contracted rates. Bidders are bound to accept the orders accordingly.

29.0 Duration

The items covered under this tender are required to be delivered and installed at USAR, East Delhi Campus of Guru Gobind Singh Indraprastha University, Surajmal Vihar, Shahdara, Delhi-110092 within 30 days.

30.0 Payment Terms

- 30.1 The payment will be released after satisfactory complete installation, demonstration, commissioning, training and receipt of performance guarantee of the product.
- Each invoice should be submitted in duplicate clearly specifying contact no, goods description, quantity, unit price, total amount, bank details along with warranty certificate, etc.
- 30.3 No advance payment will be made under any circumstances.

31.0 Delay and Non Conformance

- 31.1 If the bidder fails to Install the Equipment with in the period specified in the Purchase Order, University shall without prejudice to its other remedies under the Purchase Order, deduct from the contract price, as liquidated damages, a sum equivalent to 1% (one percent) of the contract price of the delayed goods weekly or part thereof of delay until actual delivery. The penalties will be maximum of 10% of the contract amount / awarded value.
- In case of extraordinary delay or beyond 90 days of stipulated delivery period, University reserves the right to terminate the contract, without any liability to cancellation charges, forfeit/en-cash the submitted Performance Guarantee and blacklist/debarred the defaulting firm.

32.0 Services during warranty period

- 32.1 The maximum response time for maintenance complaint during warranty period (i.e. time required for bidder's maintenance engineer to report at the installation after a request call is made or letter is written) shall not exceed 05 working days.
- 32.2 The period for correction of defects during warranty period is 3 weeks.
- 32.3 In case an item is not useable beyond the stipulated maximum downtime the bidder will be required to arrange for an immediate replacement.
- 32.4 In case the rectification of defects is not carried out within 3 week and replacement of defective items are not provided, a penalty of sum equivalent to 1% per week of the delivered price of that defective item(s) shall be levied. This penalty is applicable up to a maximum of 3 weeks (maximum 3%)

33.0 Packing and Marking

33.1 All packing should be strong enough to withstand rough handling during loading/ unloading and transporting. Fragile articles should be packed with special precaution and should bear the marking like Fragile, handle with care, This side up etc.

34.0 Substitution and Wrong Supplies

Unauthorized substitution or materials delivered in error of wrong description or quality or supplied in excess quantity or rejected goods shall be returned to the bidder at bidder's cost and risk.

35.0 Insurance, Freight and Deliveries

35.1 The supplier shall make his own arrangements towards safe and complete delivery including insurance, freight, state level permits etc. as applicable at the designated locations indicated by University in the Purchase Order.

35.2 The bidder will keep University informed about changes, if any, in various stages of deliveries, installation.

36.0 Arbitration and Settlement of Disputes:

- 36.1 University and the bidder shall make every effort to resolve amicably by direct information negotiation by difference or dispute arising between them under or in connection with the University order.
- 36.2 If after thirty (30) days from the commencement of such informal negotiations, University and the supplier are unable to resolve amicably the dispute, either party may require that the dispute be referred for resolution to the formal mechanisms as specified hereunder:
- 36.2.1 Any dispute or differences whatsoever arising between the parties out of or relating to the manufacturing, meaning, scope, operation or effect of this contract or the validity or the breach thereof shall be settled by arbitration in accordance with the provisions of the Arbitration & Conciliation Act, 1996 and the award made in pursuance thereof shall be binding on the parties. The sole arbitrator shall be appointed by the Vice Chancellor, GGS Indraprastha University.
- 36.2.2 The performance under this contract shall not stop for any reason whatsoever during the said dispute/proceedings, unless the bidder is specifically directed by University to desist from working in this behalf.
- 36.2.3 The venue of arbitration shall be Delhi/ New Delhi. The language of proceedings shall be English. The Law governing the substantive issues between the parties shall be the Laws of India. All disputes are subject to the jurisdiction of the Delhi Courts only
- 36.2.4 It is also a term of that if any fees are payable to the arbitrator, these shall be paid equally by both the parties. It is also a term of the contract that the arbitrator shall be deemed to have entered on the reference on the date he issues notice to both the parties calling them to submit their statement of claims and counter statement of claims.
- **37.0 Force Majeure** For purpose of this Clause, Force Majeure shall mean fires, floods, natural disasters or other acts, that are unanticipated or unforeseeable, and not brought about at the instance of the party claiming to be affected by such event, or which, if anticipated or foreseeable, could not be avoided or provided for, and which has caused the non-performance or delay in performance, such as war, turmoil, strikes, sabotage, explosions, quarantine restriction beyond the control of either party. A party claiming Force Majeure shall exercise reasonable diligence to seek to overcome the Force Majeure event and to mitigate the effects thereof on the performance of its obligations under this Supply Order.

If a Force Majeure situation arises, the supplier shall promptly notify the University in writing of such conditions and the cause thereof. Unless otherwise directed by the University in writing, the Supplier shall continue to perform its obligations under the Purchase Order as far as is reasonably practical, and shall seek all reasonable alternative means for performance not prevented by the Force Majeure event.

SECTION II

INFORMATION REGARDING TECHNICAL ELIGIBILITY (Annexure A to J)

LETTER OF TRANSMITTAL

From:			

To

The Registrar GGS IPU Sector 16C, Dwarka, Delhi

Sub: Submission of Tender Document for "Supply and Installation of Lab Equipments for Electronics Lab, USAR, East Delhi Campus at Guru Gobind Singh Indraprastha University, Surajmal Vihar, Delhi-110092".

Sir,

Having examined the details given in Tender document for the above work, I/we hereby submit the relevant information:-

- 1. I/we hereby certify that all the statement made and information supplied in the enclosed annexure / forms accompanying statement are true and correct.
- 2. I/we have furnished all information and details necessary for eligibility and have no further pertinent information to Supply & Installation.
- 3. I/we submit the requisite certified solvency certificate and authorize the Registrar, GGSIPU to approach Bank issuing the solvency certificate to confirm the correctness thereof. I/we also authorize the GGSIPU to approach individuals, employers, firms and corporation to verify our competence and general reputation.

Name & Signature(s) of Bidder(s) with seal

DECLARATION BY THE BIDDER

understood the Bidding Docume	(Name of the Bidder) hereby represent that we have gone through and ent (which in two parts) in Part-I (Commercial Section & Technical Section) ties) and that our Bid has been prepared accordingly in compliance with the I documents.
on each page in token of our accordeemed to form part of our bid constitution of Contract Agreem	Iding Document marked "Original" as part of our Bid duly signed and stamped eptance. We undertake that Part-I and Part-II of the Bidding Document shall be and in the event of award of work to us, the same shall be considered for ent. Further, we shall sign and stamp each page of this Part-I and Part-II as at t of the Contract in the event of award of Contract to us.
separately sealed envelope. We	we indicated prices in Schedule of Quantities and submitted in Price Bid in confirm that rate quoted by us includes price for all works/activities/supply etc. of the items in Schedule of Quantities.
SIGNATURE OF BIDDER	:
NAME OF BIDDER	:
COMPANY SEAL	:

 $\textbf{Note:} \ \text{This declaration should be signed by the Bidder's representative who is signing the Bid.}$

COMPLIANCE TO BID REQUIREMENT

We hereby agree to fully comply with, abide by and accept without variation, deviation or reservation all technical, commercial and other conditions whatsoever of the Bidding Documents and Addendum to the Bidding Documents, if any, for subject work issued by GGSIPU.

We hereby further confirm that any terms and conditions if mentioned in our bid (Un-priced as well as Priced Part) shall not be recognized and shall be treated as null and void.

SIGNATURE OF BIDDER	:	
NAME OF BIDDER	:	
COMPANY SEAL	:	

DECLARATION BY THE BIDDER

We (Nam	ne of the Bidder) hereby declare that the item for which we have quoted
our price in the Financial Bid would no	ot be an item used so far for demo/any other purposes and will be unused
(brand new).	
SIGNATURE OF BIDD	DER :
NAME OF BIDDER	:
COMPANY SEAL	:

Note: This declaration should be signed by the Bidder's representative who is signing the Bid.

ORGANISATION STRUCTURE

1.	Name & Address of the Bidder :		
2.	Telephone No./Fax No./ e-mail :		
3.	Legal status of the Bidder (attach copies of original document defining the legal status) a) An Individual b) A proprietary firm c) A firm in partnership d) A limited company or Corporation e) A Public Sector Undertaking		
4.	Particulars of registration with various Government Bodies (Attach at Organization /Place of registration Registration	tested Photo Copy) ration No	
5.	A. PAN NoB. GST No		
6.	Names and Titles of Directors & Officers with designation to be concerned with this work.	:	
7.	Name & Designation of individuals authorized to act for the organization: (Pl attach power of attorney in favour of authorized representative duly signed by authorized signatory)		
8.	Has the Bidder ever required to suspend work for a period of more than six months continuously after you commenced the business? If so, give the name of the project and reasons of suspension of work.	:	
9.	Has the Bidder, or any constituent partner in case of partnership firm, ever abandoned the awarded work before its completion? If so, give name of the project and reasons for abandonment.	:	
10.	Has the Bidder, or any constituent partner in case of partnership firm, ever been debarred/ black listed for tendering in any organization at any time? If so, give details. :		
11.	Has the Bidder, or any constituent partner in case of partnership firm, ever been convicted by a court of law? If so, give details.	:	
13.	Any other information considered necessary but not included above. :		

(Stamp, Name & Signature of Bidder)

DETAILS OF ANNUAL TURNOVER

A. FINANCIAL DETAILS

Financial Years	Gross Annual Turnover (In Lakhs)	Profit/Loss (In Lakhs)
2020-2021		
2021-2022		
2022-2023		

B. Audited balance sheet and profit & loss account for above three years to be submitted. Must be attested by the Chartered Accountant.

Signature & stamp by Chartered Accountant

(Stamp, Name & Signature of Bidder)

DETAILS OF SUPPLY OF ITEMS (AS PER SPECIFICATION GIVEN IN SECTION III BELOW) IN LAST 03 (THREE) YEARS

S. No.	POSTAL ADDRESS OF CLIENT WITH CONTACT NUMBERS	STARTING DATE	SCHEDULED COMPLETION DATE	ACTUAL COMPLETIO N DATE	REASONS FOR DELAY, IF, ANY

(Stamp, Name & Signature of Bidder)

DECLARATION FOR FAIR BUSINESS BY THE BIDDER

This is to	certify that We, M/s	in submission of this offer conf	irm that:-
i)	We have not made any misleading or fals attachments in proof of the qualification requir		statements and
ii)	We do not have records of poor performan completing the contract, inordinate delays in cetc.		
iii)	Business has not been banned with us by any Sector Undertaking or Enterprise of Central / S		partment/ Public
iv)	We have submitted all the supporting documents prescribed format.	nents and furnished the relevan	nt details as per
v)	The information and documents submitted wiresponsible for the correctness of the information		
vi)	We understood that in case of any statement furnished by us in connection with this offer is will be fortified and business dealings will be be	s found to be incorrect or false,	
vii)	We have not been punished / penalized by way	of imprisonment in last three ye	ars.
viii)	We have not been blacklisted/ debarred by any three years.	of the Government/Public Sector	or Agency in last
	SE	EAL, SIGNATURE & NAME O	F THE BIDDER
		Signir	g this document

Form of Performance Guarantee Bank Guarantee Bond

1.	In consideration of the GGSIPU (hereinafter called "The University") having offered to accept the terms and conditions of the proposed agreement between and (hereinafter called "the said bidder(s)") for the work
	(hereinafter called "the said agreement") having agreed to production of a irrevocable Bank Guarantee for Rs (Rupees only) as a
	security/guarantee from the bidder (s) for compliance of his obligations in accordance with the terms and condition in the said agreement.
	We, (indicate the name of the Bank) (hereinafter referred as "the Bank") hereby undertake to pay to the University an amount not exceeding Rs (Rupees only) on demand by the University.
2.	We,(indicate the name of the Bank) do hereby undertake to pay the amounts due and payable under this guarantee without any demure, merely on a demand from the University stating that the amount claimed is required to meet the recoveries due or likely to be due from the said bidder (s). Any such demand made on the bank shall be conclusive as regards the amount due and payable by the bank under this Guarantee. However, our liability under this guarantee shall be restricted to an amount not exceeding Rs (Rupees
3.	We, the said bank further undertake to pay the University any money so demanded notwithstanding any dispute or disputes raised by the bidder(s) in any suit or proceeding pending before any court or Tribunal relating thereto, our liability under this present being absolute and unequivocal.
	The payment so made by us under this bond shall be a valid discharge of our liability for payment there under and the bidder(s) shall have no claim against us for making such payment.
4.	We,(indicate the name of the Bank) further agree that the guarantee herein contained shall remain in full force and effect during the period that would be taken for the performance of the said agreement and that it shall continue to be enforceable till all the dues of the University under or by virtue of the said agreement have been fully paid and its claims satisfied or discharged or till Project-in-Charge on behalf of the University certified that the terms and conditions of the said agreement have been fully and properly carried out by the said
_	bidder(s) and accordingly discharges this guarantee.
5.	We,(indicate the name of the Bank) further agree with the University that the University shall have the fullest liberty without our consent and without affecting in any manner our obligation hereunder to vary any of the terms and conditions of the said agreement or to extend time of performance by the said bidder(s) from time to time or to postpone for any time or from time to time any of the powers exercisable by the University against the said bidder(s) and to forbear or enforce any of the terms and conditions relating to the said agreement and we shall not be relieved from our liability by reason of any such variation, or extension being granted to the said bidder(s) or for any forbearance, act of omission on the part of the University or any indulgence by the University to the said bidder(s) or by any such matter or thing whatsoever which under the law relating to sureties would, but for this provision, have effect of so relieving us.
6.	This guarantee will not be discharged due to the change in the constitution of the Bank or the bidder(s).
7.	We,(indicate the name of the Bank) lastly undertake not to revoke
8.	this guarantee except with the previous consent of the University in writing. This guarantee shall be valid upto unless extended on demand by the University. Notwithstanding anything mentioned above, our liability against this guarantee is restricted to Rs (Rupees only) and unless a claim in writing is lodged with us within six months of the date of expiry or the extended date of expiry of this guarantee all our liabilities under this guarantee shall stand discharged.
Dated t	he day of for (indicate the name of the Bank)

Annexure-G

SECTION III

TECHNICAL SPECIFICATIONS

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
1.	Training Platform to Study Characteristics of MOSFET, FET & UJT Training Platform should have: DC Fixed Power Supply: -5V, +15V, +35V DC Variable Power Supply: 1.5V to 14 V; 1.5V to 34V Digital Voltmeter: 0-200V; Digital Ammeter: 0-200mA (Range selectable) Bread Board: Dimension (mm): 175 x 61 x 10; Distribution strips: 2 Distribution holes: 200; Terminal Strips: 1; Terminal holes: 640 Resistor Bank: M.F.R. 100Ω 1W (3 Nos.) M.F.R. 470Ω 1W (3 Nos.); M.F.R. 1KΩ 1W(3 Nos.); Variable Resistances: 5 KΩ Ten turn Potentiometer (1 No.) 10 KΩ 10 turn Potentiometer (1 No); 5 KΩ Single turn Potentiometer (1No) Mains Supply: 90-230V, 50Hz; Fuse: 500 mA, slow blow Interconnections: 2mm sockets & 2 mm Patch cords stackable Trainer should be on legend PCB, encased in a plastic box with cover to protect it from dust. No circuitry components on the top of board only block diagram should be provided on top of trainer board.	10	Rs.2,05,000	Rs.6,150
2.	Multivibrator Trainer Trainer should be used to study Monostable & Astable Multivibrator Technical Specifications- DC Bias Voltage: +5V; Frequency of Trigger: 1KHz Pulse Generator: Frequency Range of Astable Multivibrator: 600Hz – 3.2KHz (approx.); Frequency Range of Bistable Multivibrator: 350Hz – 1KHz (approx.) Output Voltage: 5 Vpp (approx.) Interconnection: 2 mm sockets & Sufficient Nos of stackable patch cords. Trainer should be on Legend PCB. Housed in a Moulded case with moulded cover. Circuit diagram should be printed on the top of the board	10	Rs. 98,000/-	Rs.2,940

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
3.	Operational Amplifier Based circuit design Training Platform The Trainer should have two op Amps with Pins brought on top of board ,on-board Resistor, Capacitor and potentiometer of different Values. Bread-board should be provide on the trainer for construction of circuits using external components along with on-board resources like frequency generator & DC Power supplies. The Trainer should have : Fixed DC Power Supply : ± 1.5 V to ± 10 V, regulated; Variable DC Supply : ± 1.5 V to ± 10 V, regulated Function/Frequency Generator :Sine , Square & Triangular : Frequency : 1 kHz to 100 kHz ; controlled by 10 turn pot. Amplitude : 0-5 Vpp variable (Sine & Triangle) ; Square wave : 5 Vpp fixed Bread Board : Dimension(mm) : 175 x 61 x 10 ; Distribution strips : 2 ; Distribution holes : 200 ;Terminal holes : 640 Op-amp : IC 741 (2 Nos.)All pins terminated on 2 mm Banana Sockets Supply Voltage : ± 22 V max. ;Differential Input Voltage : ± 30 V max. Input Voltage : ± 15 V max.; Slew Rate : 0.5 V/μs (VCC = ± 15 V) On board Components : SMD Resistance 1 KΩ ± 10 (S Nos.) each ; Diode : Diode 1N 4007; On board Capacitor Bank : Electrolyte Cap. ± 10 1mf/63V; Disc cap. ± 10 1mf/63V ; ± 10 1mf/63V variable Resistance bank: ± 10 1K ± 10 Nos. ± 10 2mm sockets , Patch cords : 2 mm banana stackable, Mains Power Supply: 90 - 240V ± 10 %, 50Hz Trainer should be on Legend PCB with no components on the top of board. Should be housed in Plastic protected case with cover attached to it . Should be supplied with a Virtual lab software containing theory & simulation & Animation on Analog electronics with a USB-based Hardware lock which is a pen drive provided with development platform.	10	Rs. 2,40,000/-	Rs.7,200
4.	Analog Electronics Development Platform DC Power Supplies: + 5V, 1 A (Fixed); ± 12V, 500 mA (Fixed); 0 to ± 12V, 500 mA (Variable); AC Supply: 9V-0V-9V, 500mA; Breadboard: Breadboard for making various circuits. On Board Function generator: Waveform: Sine, Square & Triangular. Freq. range 1Hz to 100 KHz. Volt/Current/Frequency Measurement: Measurement display on 16X2 LCD; 2 Voltage inputs /2 current inputs & One frequency input Voltage measurement Range + 12V to -12V; Current Measurement Range 0 to 500mA Frequency measurement Range DC to 100KHz; (All with respect to Ground) PC Interface: Acquisition from 2 Analog input channels (Max. input 1Volt) Continuity Tester: For testing the continuity. Provided with Beeper Sound. Power Supply: 110-220 V ±10%, 50Hz. Interconnections: 2 mm Sockets & 2 mm stackable patch cords. Trainer should be on legend PCB, encased in a plastic box	25	Rs.5,00,000/-	Rs.20,888/- (for item no.4 to 4.13)

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
	with cover to protect it from dust . No circuitry components on the top of board only block diagram should be provided on top of trainer board. Should be compatible with External Analog circuit boards, Breadboard can be replaced with Analog circuit boards with Supply & signal from main board & measurements on main board. Should be supplied with a Virtual Lab software containing theory & simulation & Animation on Analog electronics with a USB-based Hardware lock which is a pen drive provided with development platform			
4.1	Should be provided with one additional breadboard Analog Daughter boards to be supplied compatible with			
	main Analog Electronics Development Platform			
	Diode Characteristics with Silicon, Zener & LED The board should be on Glass Epoxy PCB with no components on the top of the Board Diode Characteristics with Silicon, Zener & LED circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board.	05	Rs. 13,000/-	
4.2	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Transistor Characteristics Common Base-NPN The board should be on Glass Epoxy PCB with no components on the top of the Board, Transistor Characteristics Common Base-NPN circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.15,000/-	
4.3	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform Transistor Characteristics Common Base-PNP The board should be on Glass Epoxy PCB with no components on the top of the Board, Transistor Characteristics Common Base-PNP circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.15,000/-	
4.4	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform Transistor Characteristics Common Emitter-NPN The board should be on Glass Epoxy PCB with no components on the top of the Board, Transistor Characteristics Common Emitter -NPN circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.15,000/-	
4.5	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform Transistor Characteristics Common Emitter-PNP The board should be on Glass Epoxy PCB with no components on the top of the Board, Transistor Characteristics Common Emitter-PNP circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.15,000/-	

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
4.6	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Rectifier Circuits The board should be on Glass Epoxy PCB with no components on the top of the Board, Rectifier circuits should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board.	05	Rs.13,000/-	
4.7	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	RC Coupled amplifier The board should be on Glass Epoxy PCB with no components on the top of the Board, RC Coupled amplifier circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.16,250/-	
4.8	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Class A Amplifier The board should be on Glass Epoxy PCB with no components on the top of the Board, Class A Amplifier circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform .2mm sockets provided for connections on the board	05	Rs.12,000/-	
4.9	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Class B Push Pull Emitter Follower The board should be on Glass Epoxy PCB with no components on the top of the Board, Class B Push Pull Emitter Follower circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.15,500/-	
4.10	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Class C Tuned Amplifier The board should be on Glass Epoxy PCB with no components on the top of the Board, Class C Tuned Amplifier circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.15,500/-	
4.11	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Zener Voltage Regulator The board should be on Glass Epoxy PCB with no components on the top of the Board, Zener Voltage Regulator circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform .2mm sockets provided for connections on the board	05	Rs.13,000/-	
4.12	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Diode Clippers The board should be on Glass Epoxy PCB with no components on the top of the Board, Diode Clipper circuit should be printed on the PCB. Power supply & signal generator inputs to be	05	Rs.19,000/-	

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
	provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board		(4.55.45.45.45.45.45.45.45.45.45.45.45.45	
4.13	Analog Daughter boards to be supplied compatible with main Analog Electronics Development Platform			
	Diode Clamper The board should be on Glass Epoxy PCB with no components on the top of the Board, Diode Clamper circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from the main Analog Electronics Development Platform.2mm sockets provided for connections on the board	05	Rs.19,000/-	
5.	70 MHz Dual channel Digital Storage Oscilloscope No of Analog Channels: 02, Bandwidth: 70 MHz Sampling Rate: 1 GS/s sample rate on all channels simultaneously Record length: 20k point record length on all channels Input sensitivity range: 1 mV/div to 10 V/div with Vertical zoom to Vertically expand or compress a live or stopped waveform Input impedance 1 MΩ ±2 % in parallel with 14 pF ±2 pF Acq. modes: Sample ,Peak Detect, Average, Hi-Resolution & Roll mode Timebase Range: 2 ns/div to 100 sec/div with Horizontal zoom to Horizontally expand or compress a live or stopped waveform Timebase Accuracy: 25ppm Advanced triggers include pulse, runt, and line triggers 7-inch WVGA color display with 15 horizontal divisions 32 automated measurements, Dual window FFT with simultaneous time and frequency domain views ,Trigger frequency counter ,Pan and Zoom capability Fan less design contributes to low noise operation. Interface: USB Host & device, Help Menu selection facility for on-screen tips for users Mains Supply: 100 to 240 VAC RMS ±10%/45 Hz to 65 Hz Built-in oscilloscope handbook for operating instructions and oscilloscope fundamentals Should have Integrated courseware feature for lab exercise/Experiment guidance on the display, Facility to Disable Autoset, Cursors, and Automated measurements to help students to learn basic concepts of Oscilloscope. Manufacturer should have service center & NABL Accredited Lab in India.	15	Rs.12,00,000/-	Rs.36,000
6.	25 MHz Dual Channel Function Generator No. of Channels: 2 Type of Waveforms: Sine, Square ,Pulse, Ramp, Noise & at least 45 types of arbitrary waveforms Frequency: Sine: 1μ Hz to 25 MHz; Square: 1μ Hz to 12.5 MHz Pulse: 1μ Hz to 12.5 MHz; Ramp: 1μ Hz to 1 MHz; Noise: 25MHz & 45 arbitrary waveforms Arbitrary: 1μ Hz to 10MHz, Memory Length 2 to 8192 Points. Sampling Rate: 125 Ms/s; Analog Bandwidth for Arb. waveform: 30 MHz 64-MByte internal non-volatile memory for arbitrary waveform storage Continuous, sweeping, burst, and modulation modes (AM, FM, PM, FSK) Facility for DC offset Amplitude: 2mVp-p to 20 Vp-p open circuit; 14bit vertical resolution Local impedance setting Selectable & Variable: 50 Ω & 1 Ω to 10.000 kΩ, (Amplitude Display should automatically adjust	15	Rs.12,00,000/-	Rs.36,000

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
	according to selected load impedance) Built-in 200 MHz counter with 6-digit resolution with Frequency /period/pulse width /duty cycle measurement Standard USB host/device interface Software for waveforms editing by an external USB memory stick Frequency Resolution: 1 µ Hz or 12 Digits Internal reference Stability: ±1 ppm at 0 - 40 °C, Auxiliary inputs and outputs: External modulation input Display: 3.95-inch colour LCD; resolution 480 by 320; 65,536 colours Accessories: USB cable, BNC to BNC cables-2 nos, Mains Chord.			
	Manufacturer should have service centre & NABL Accredited Lab in India			
7.1	Digital Electronics Development Platform It should have following features: On Board DC Power supply; On Board 1 MHz Pulse Generator with TTL/CMOS mode Pulser switches, 8 bit data switches; Bicolor LED display & Logic probe BCD to Seven Segment Display; CMOS/TTL outputs; Functional blocks indicated on board mimic; Breadboard: 172.5 mm 128.5 mm; Tie points: 1685 DC Power Supply:+5 V /1 A, 5 V /500 mA; ±3 V to ±15 V /500 mA (variable), Pulse Generator: Freq.range: 1 Hz to 1 MHz in 6 steps. Variable in between Amplitude: 3 V -15 V (CMOS), 5 V(TTL); Duty cycle: 50 %, TTL / CMOS Pulser Switches: 2 Nos. (Push to On); Data switches: 8 Nos. (Toggle switches for both TTL & CMOS); LED display:8 Nos. (TTL/CMOS Mode); Seven Segment Display: 3 Nos Logic Probe:: Logic level indicator for TTL/CMOS Power Supply: 110-220V ±10%, 50Hz (Detachable Mains Cord to be provided) Trainer should be on legend PCB, encased in a plastic box with cover to protect it from dust. No circuitry components on the top of board only block diagram should be provided on top of trainer board. Should be compatible with External Digital circuit boards, Breadboard can be replaced with Digital circuit boards with Supply & signal from main board & measurements on main board. Should be supplied with a Virtual Lab software containing theory & simulation & Animation on Digital electronics with a USB-based Hardware lock which is a pen drive provided with the development platform. Should be provided with one additional breadboard Digital Daughter boards to be supplied compatible with main Digital Electronics Platform	15	Rs.3,15,000/-	Rs.12,150/- (for items at sl.no.7 to 7.6)
	Logic Gate Trainer Board Board should be on Glass Epoxy PCB with no components on the top of the Board. Logic Gates circuits for AND, or, NOR, NOT, NAND, EX-OR should ld be printed on the PCB. Power supply & signal generator inputs to be provided from main Digital Electronics Platform.2mm sockets provided for connections on the board	05	Rs.15,000/-	

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
7.2	Digital Daughter boards to be supplied compatible with main Digital Electronics Platform		(
	Flip Flop Trainer Board Board should be on Glass Epoxy PCB with no components on the top of the Flip Flop circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from main Digital Electronics Platform. 2mm sockets provided for connections on the board	05	Rs.15,000/	
7.3	Digital Daughter boards to be supplied compatible with main Digital Electronics Platform Shift Register Trainer Board	05	D 15 000/	
	Board should be on Glass Epoxy PCB with no components on the top of the Board Shift registers circuit should be printed on the PCB. Power supply & signal generator inputs to be provided from main Digital Electronics Platform. 2mm sockets provided for connections on the board	05	Rs.15,000/	
7.4	Digital Daughter boards to be supplied compatible with main Digital Electronics Platform Adder-Subtractor Trainer Board			
	Board should be on Glass Epoxy PCB with no components on the top of the Board . 4 Bit parallel adder/subtractor circuit should be printed on the PCB .Power supply & signal generator inputs to be provided from main Digital Electronics Platform.2mm sockets provided for connections on the board	05	Rs.15,000/	
7.5	Digital Daughter boards to be supplied compatible with main Digital Electronics Platform			
	Multiplexer-Demultiplexer Trainer Board Board should be on Glass Epoxy PCB with no components on the top of the Board .Multiplexer/Demultiplexer circuit should ld be printed on the PCB. Power supply & signal generator inputs to be provided from main Digital Electronics Platform.2mm sockets provided for connections on the board	05	Rs.15,000/	
7.6	Digital Daughter boards to be supplied compatible with main Digital Electronics Platform			
	Counter Trainer Board Board should be on Glass Epoxy PCB with no components on the top of the Board 4 bit Synchronous Binary Counter circuit should be printed on the PCB .Power supply & signal generator inputs to be provided from main Digital Electronics Platform.2mm sockets provided for connections on the board.	05	Rs.15,000/	
8.	Universal IC Tester: Tests a wide range of Analog & Digital IC's such as 74 Series,40/45 Series of CMOS IC's.,OP-Amps, 555 etc Should have Auto search facility for Digital ICs. Should Test by: Truth table/sequence table comparison. On Board Zif Sockets: 40 pin & 28 pin DIP ZIF sockets. Keys: 20 Touch- keys Key pad with numerical & functional keys. Display: 16x2 LCD Display.			
	mains Supply Input Voltage: 230V AC IC Tester should have facility to test Micro- processor ,Peripherals & Memory IC's Anaog IC's such Op-amp, 555 Timers ,Transistor Arrays, Analog switches, Cross Point Switch,Opto- couplers, 8 bit ADC, 8 bit DAC, Comparators TTL IC's(74xx & 74xxx Series): 00 01 02 03 04 05 06 07 08 09 10 11 12 13 14 15 16 17 18 19 20 21 22 24 25 26 27 28 30 32 33 37 38 39 40 42 43 44 45 46 47 48 49 50 51 54 55	02	Rs.75,000/-	Rs. 2,250/-
	30 32 33 37 38 39 40 42 43 44 45 46 47 48 49 50 51 54 55 64 70 72 73 74 75 76 77 80 82 83 85 86 87 90 92 93 94 95 96 101 102 103 016 107 108 019 112 113 114 125 126 128			

132 133 134 155 156 157 158 160 161 162 163 164 165 166 168 169 170 173 174 175 176 177 180 182 190 191 192 193 194 195 196 197 198 199 240 241 242 243 244 245 247 274 249 251 253 256 257 258 259 260 266 273 279 280 283 290 293 CMOS IC's (40xx & 40xxx Series): 00 01 02 06 08 09 10 11 12 13 14 15 17 18 19 20 21 22 23 24 25 26 27 28 29 30 32 33 34 35 37 38 40 41 42 43 44 48 49 50 51 52 53 63 66 68 69 70 71 72 73 75 76 77 78 81 82 85 86 93 94 95 96 99 101 102 103 104 106 107 117 147 160 161 162 163 174 175 182 192 193 CMOS IC's (45 Series): 4501 4502 4503 4506 4508 4510 4511 4512 4513 4514 4515 4516 4518 4519 4520 4529 4530 4531 4532 4543 4553 4554 4555 4560 4561 4572 4584 4585 4724, 93 and 96 series IC's: 9300 9301 9302 9309 Microprocessor IC's: 8088 8085 Z-80CPU(8400) 6502 Peripherals IC's: 8155 8251 8253 8255 8259 8279 Z-80 PIO(8420) 8121 8123 8205 8212 8216 8221 8226 8555, Memory IC's: 2716 2732 2764 27128 27256 27512 2147 6116 6264 62256 4164 DS7810 DS7811 DS7812 DS7819 LINEAR IC's Operational Amplifiers: Lm101 LM107 LM108 LM112 LM124 LM143 LM144 LM148 LM149 LM158 LM192 LM201 LM207 LM307 LM308 LM312 LM316 LM324 LM343 LM344 LM348 LM349 LM351 LF356 LF357 LM358 LM392 LM709 LM714 LM725 LM741 (8/14 pin) LM747 (10/14 pin) LM748 LM1458 LM1558 LM2902 LM2924 LM3301 LM3401 HA17080	
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LINEAR IC's Operational Amplifiers: Lm101 LM107 LM108 LM112 LM124 LM143 LM144 LM148 LM149 LM158 LM192 LM201 LM207 LM307 LM308 LM312 LM316 LM324 LM343 LM344 LM348 LM349 LM351 LF356 LF357 LM358 LM392 LM709 LM714 LM725 LM741 (8/14 pin) LM747 (10/14 pin) LM748 LM1458 LM1558 LM2902 LM2924 LM3301 LM3401 HA17080	
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LM1558 LM2902 LM2924 LM3301 LM3401 HA17080	
HA17082 HA17083 HA17084 HA17301 HA17324	
HA17358 HA17458 HA17474 HA17558 HA17741(8/14 pin)	
HA17747 HA17902 HA17904 UCOP01 UCOP02 OP07 OP27 CA3130 CA3140 TL074 TL084	
Comparators : LM111(8/14 pin) LF111 LM119	
LM139LM160(8/14 pin) LM161 LM193 LM211(8/14pin)	
LF211 LM219 LM239 LM260(8/14 pin) LM261 LM293 LM311(8/14pin) LF311 LM319 LM339 LM360 (8/14pin)	
LM361 LM393 LH2111 LH2211 LH2311 LM2901 LM3302	
HA17339 HA17393 HA17901 HA17903	
Transistor Arrays :ULN2001 ULN2002 ULN2003 ULN2004	
ULN2005 ULN2064 ULN2065 ULN2066 ULN2067 ULN2068 ULN2069 ULN2074 ULN2075 TD62501	
TD62502 TD62503 TD62504 TD62505 TD62506 TD62507	
75064 75065 75066 75067 75068 75069 75074 75075 75430	
75446 75447 75448 75449 75450 75460 75465 75466 75467 75468 75469 75470 75491 75492	
Opto Couplers :MCT2 MCT2E 4N25 4N26 4N27 4N28	
4N32 4N33 4N35 4N36 4N37 6N135 6N136 6N137 6N138	
6N139 TIL111 TIL112 TIL113 TIL114 TIL115 TIL116 TIL117 TIL118 TIL119 TIL127 TIL128 TIL153 TIL154	
TIL155 TIL156 TIL157 TIL181 TIL189 TIL190 MOC3009	
MOC3010 MOC3011 MOC3012 MOC3020 MOC3021	
MOC3022 MOC3023 HCPL2502 HCPL2601 HCPL2630	
OPI8012 OPI8013 OPI8014 OPI8015 Analog Switches: CD4016 CD4066 CD4051 CD4052	
CD4053 HI200 HI201 HI300 HI301 HI302 HI303 HI304	
HI305 HI306 HI307	
Cross Point Switches: CD22100 Voltage Followers LM102 LM202 LM302 LM110 (14 pin) LM210 (14 pin) LM310	
(8/14 pin) LM210 LM2210 LM2310	
Timers LM555 NE555 HA17555	
A to D Converters ADC0801 ADC0802 ADC0803	
ADC0804 D to A Converters DAC0800 DAC0806 DAC0807	
DAC0808 HA17008R HA17408 General Linear IC's 75182	

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
	75183 75189 DS7820A DS8820A DS8830 MC1489, Should be provided with one tool kit containing Screwdriver set, nose plier, wire cutter & hammer		, , , , , , , , , , , , , , , , , , , ,	
9.	Multiple Output Benchtop DC Power Supply No. of outputs: 03 outputs Output 1: 0-30 V 0-3A ;Output 2: 0-30 V 0-3A ;Output 3: 0-5V/0-3A Max. output Power: 195W All Three outputs should be Isolated from each other & ground, should be independent, and adjustable. Tracking And Combination Modes Output DC power with less than 5mVp-p noise Display voltage and current measurements continuously from all three outputs Should have facility to Store frequently used configurations in any of 30 setup memory locations Should have facility to turn off any output after a predetermined test time with each channel's output timer Facility to Adjust the outputs with the rotary knob or using the keypad with setting resolution of 10mV or 1mA. Overvoltage protection setting for each output should be provided. Load & Line Regulation: Voltage: ≤0.02% + 4mV; Current: ≤0.2% + 3mA Ripple And Noise: Voltage: ≤1mvrms/≤5mVpp; Current: ≤6marms Setting Resolution: Voltage: 10mV; Current: 1mA Setting Accuracy: Voltage: ≤0.06% + 20mV; Current: ≤0.2% + 10mA Readback Accuracy: Voltage: ≤0.06% + 20mV Current: ≤0.2% + 10mA Readback Resolution: Voltage: 10mV Current: 1mA Readback Accuracy: Voltage: ≤0.06% + 20mV Current: ≤0.2% + 10mA Isolation Voltage, Output To Chassis: Facility to isolate Any output up to 240V (DC + peak AC with AC limited to a maximum of 3Vpk-pk and a maximum of 60Hz) relative to the earth ground terminal. Isolation Voltage, Output To Output: Facility to isolate Any output can be isolated up to 240V (DC + peak AC with AC limited to a maximum of 3Vpk-pk and a maximum of 60Hz) relative to any other output terminal. Display: Vacuum fluorescent display simultaneous for all Three output voltage & current. Output Timer Range: 0.1s to 99999.9s Protection & Safety: Overtemperature Protection: in case the internal temperature of the supply exceeds 85°C, the supply should automatically turn off. EMC Compliance: Should Conforms to European Union EMC Directive. Safety Compliance: Conforms to European Union Low Voltage Directive. Mains Power S	10	Rs.8,00,000/-	Rs. 24,000/-
10.		25	Rs.90,000/-	Rs. 2,700/-

Sl.No.	SPECIFICATIONS	Quantity	Total Estimated price (inclusive GST)	EMD (Rs.)@3%
	Hold measurement. Relative measurement, Duty cycle (%) measurement Temperature measurement with K type Thermocouple Backlit Facility			

SECTION IV

FINANCIAL BID

Supply and Installation of Supply and Installation of Lab Equipments for Electronics Lab, USAR, East Delhi Campus at Guru Gobind Singh Indraprastha University, Surajmal Vihar, Delhi-110092.

S. No.	Description	Qty.	Unit Cost (in Rs.)	GST	Total Amount (in Rs.)	
1.	Training Platform to Study Characteristics of MOSFET, FET & UJT	10				
2.	Multivibrator Trainer	10				
3.	Operational Amplifier Based Circuit Design Training Plat form	10				
4.	Analog Electronics Development Platform	25				
4.1	Diode Characteristics with Silicon, Zener & LED	5				
4.2	Transistor Characteristics Common Base-NPN	5				
4.3	Transistor Characteristics Common Base-PNP	5				
4.4	Transistor Characteristics Common Emitter - NPN	5				
4.5	Transistor Characteristics Common Emitter - PNP	5				
4.6	Rectifier Circuits	5				
4.7	RC Coupled amplifier	5				
4.8	Class A Amplifier	5				
4.9	Class B Push Pull Emitter Follower	5				
4.10	Class C Tuned Amplifier	5				
4.11	Zener voltage Regulator	5				
4.12	Diode Clippers	5				
4.13	Diode Clamper	5				
5.	70 MHz Dual channel Digital Storage Oscilloscope	15				
6.	25 MHz Dual Channel Function Gernator	15				
7.	Digital electronics Development Platform	15				
7.1	Logic Gate Trainer Board	5				
7.2	Flip Flop Trainer BOARD	5				
7.3	Shift Register Trainer Board	5				
7.4	Adder-Subtractor Trainer Board	5				
7.5	Multiplexer-Demultiplexer Trainer Board	5				
7.6	Counter Trainer Board	5				
8.	Universal IC Tester	2				
9.	Multiple Output Benchtop DC Power Supply	10				
10.	Digital Multimeter	25				
	Total Amount in Rs.(including all taxes	s, GST)				

Note:-

- 1. The item wise lowest financial bidder separately shall only be considered for award of work.
- 2. The bidder shall provide 60 months warranty on all items from the last date of installation and shall be responsible for any defects that develop in the item. They shall also replace any defective part of the product supplied and other accessories, without any exception and recourse, free of cost. The period of warrantee will automatically treated as extended beyond 60 months if the instrument remain non functional more than 15 days after reporting non-functional.
- 3. The rates of the items supplied by the bidder through local market/India must be quoted in INR only.

(SEAL, SIGNATURE & NAME OF THE BIDDER)

BID SECURING DECLARATION

I(Name of the Bidder)	Designation,
of (Name of the Company) do hereby subm	nit this Bid Securing
Undertaking that, if I withdraw or modify my Bid during the validity of	or, if I am awarded the
contract and failed to sign the contract or to submit the Performance	ce security before the
deadline defined in the tender document, I shall be suspended for the	period specified in the
tender document from being eligible to submit Bids for contract with	the entity that invited
the Bids.	

Name of the Bidder Name of the Company Dated

Procurement of GOODS

Form 1.2: Eligibility Declarations

disqualifications.

- c) Do not have any association (as bidder/ partner/ Director/ employee in any capacity) with such retired public official or near relations of such officials of Procuring Entity, as counter-indicated, in the Tender Document.
- We certify that we fulfil any other additional eligibility condition if prescribed in Tender Document.
- e) We have no conflict of interest, which substantially affects fair competition. The prices quoted are competitive and without adopting any unfair/unethical/anti-competitive means. No attempt has been made or shall be made by us to induce any other bidder to submit or not to submit an offer to restrict competition.
- 5) Restrictions on procurement from bidders from a country or countries, or a class of countries under Rule 144 (xi) of the General Financial Rules 2017: We certify as under:

"We have read the clause regarding restrictions on procurement from a bidder of a country which shares a land border with India and on sub-contracting to contractors from such countries, and solemnly certify that we fulfil all requirements in this regard and are eligible to be considered. We certify that:

- (a) we are not from such a country or, if from such a country, we are registered with the Competent Authority (copy enclosed), and;
- (b) we shall not subcontract any work to a contractor from such countries unless such contractor is registered with the Competent Authority.

6) MSME Status:

Having read and understood the Public Procurement Policy for Micro and Small Enterprises (MSEs) Order, 2012 (as amended and revised till date), and solemnly declare the following:

- a) We are Micro/ Small/ Medium Enterprise/ SSI/ Govt. Deptt. / PSU/ Others:....
- b) We attach herewith, Udhyam Registration Certificate with the Udhyam Registration Number as proof of our being MSE registered on the Udhyam Registration Portal. The certificate is the latest up to the deadline for submission of the bid.
- c) Whether Proprietor/ Partner belongs to SC/ST or Women category. (Please specify names and percentage of shares held by SC/ST Partners):.....

7) Start-up Status

we confirm that we \square are/ \square are not a Start-up entity as per the definition of the Department of Promotion of Industrial and Internal Trade – DPIIT.

8) Make in India Status:

Having read and understood the Public Procurement (Preference to Make in India PPP - MII) Order, 2017 (as amended and revised till date) and related

notifications from the relevant Nodal Ministry/ Department, and solemnly declare the following:

(a) Self-Certification for the category of suppliers:

(Provide a certificate from statutory auditors/ cost accountant in case of Tenders above Rs 10 Crore for Class-I or Class-II Local Suppliers). Details of local content and location(s) at which value addition is made are as follows:

Local Content	and	%age		
Location(s)	of	value	Long	
addition			·	

Therefore, we certify that we qualify for the following category of the supplier (tick the appropriate category):

- Class-I Local Supplier/
- Class-II Local Supplier/
- Non-Local Supplier.

(b) We also declare that

- There is no country whose bidders have been notified as ineligible on a reciprocal basis under this order for an offered Goods, or
- We do not belong to any Country whose bidders are notified as ineligible on a reciprocal basis under this order for the offered Goods.

9) Self-Declaration by Indian Agents/ Associates of Foreign Principals

- (a) Self-attested documentary evidence about their identity (PAN, Aadhar Card, GSTIN registration, proof of address, etc.), business details (ownership pattern and documents, type of firm, year of establishment, sister concerns etc.) to establish that they are a bonafide business as per Indian Laws – are submitted as part of Form 1.1 annexed herewith.
- (b) Agency Agreement shall be submitted with Form 1.4. It shall cover
 - (i) the precise relationship, services to be rendered, mutual interests in business generally and/ or specifically for the tender and
 - (ii) any payment the agent or associate receives in India or abroad from the foreign OEM/ principal, whether a commission or a general retainer fee.
- (c) Our Foreign principals, explicitly authorizing us to make an offer in response to the tender, either directly or in association with them, are listed in Form 1.3 and 1.4 annexed herewith. That also indicates their name, address, nationality, status (i.e., whether manufacturer or agents of manufacturer holding the Letter of Authority of the Principal).
- (d) The amount of commission/remuneration included in the price (s) quoted by Bidder for agents or associated bidder is detailed in Form 1.4.
- (e) Confirmation is given in Form 1.4 annexed herewith from the foreign principals that the commission/ remuneration, reserved for Bidder in the quoted price(s), if any, shall be paid by the Procuring Entity in India, in

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equivalent Indian Rupees on satisfactory completion of the Project or supplies of Goods and Spares.

10)Penalties for false or misleading declarations:

We hereby confirm that the particulars given above are factually correct and nothing is concealed and undertake to advise any future changes to the above details. We understand that any wrong or misleading self-declaration would violate the Code of Integrity and attract penalties as mentioned in this Tender Document.

(Signature with date)
(Name and designation) Duly authorized to sign bid for and on behalf of
[name & address of Bidder and seal of company] DA: As in Sr 9 to 14 above, as applicable